FARADAYIC® ElectroCell: Printed Circuit Board Pilot-Scale Facility

Objective:

This pilot-scale facility was developed to incorporate and demonstrate the capabilities of using the patented FARADAYIC® Process to deposit or etch copper for printed circuit board applications.

Summary:

Faraday established an in-house printed circuit board plating operation for test panels. This pilot-scale facility, the FARADAYIC® ElectroCell, fully replicates state-of-the-art commercial production lines and incorporates advance plating cell design concepts including a fully equipped and patented E-CHANGE™ System for in-situ rinse water recycling.

Background:

Faraday's ElectroCell has been financially supported by the US Missile Defense Agency, Multilayer Technology (a wholly owned subsidiary of Flextronics International – NASDAQ Symbol – FLEX), and the Faraday Technology Marketing Group, an intellectual property asset management company.

Operation of this pilot-scale facility is in conjunction with Ludy SystemTechnik, a market leader for advanced circuit board plating line technology, Hendor – PE, a market leader for advanced circuit board plating rectification equipment, and Prof. Alan West of Columbia University, a recognized expert in the field. The Wright Technology Network (WTN) is providing technology transfer support between Faraday and the Department of Defense.

The facility's mission is to advance the state-of-the-art for processing high density interconnect and chip-scale package electronic circuit cards, including advances in electroplating and electrochemical etching.

The FARADAYIC® Process technology illustrated above is protected by a substantial patent portfolio including issued, allowed, and pending patent actions.

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